CFP2 Series Connector Product Specification S6081C Rev 1.0

Amphenol

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Overview

This short form Product Specification defines the general use and performance parameters for Amphenol's CFP2 series connector.

The interconnect system comprises a 104 position 0.6 mm pitch connector designed to be compatible with the 100G Form factor Pluggable (CFP) Multi-source Agreement.

Availability: In Production

Usage

The connector system is capable of data rates up to 10 Gbps per channel (up to 10 channels) or 25 Gbps per channel (up to 8 channels) with resonance dampening for improved signal integrity (104 position connector).

Applications

Intended for use in high speed serial interconnect applications such as:

- Clusters
- Servers
- Storage devices

General Requirements

Connectors are tape and reel packaged for robotic pick-and-place.

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Revision Date: May 4, 2011

38 POSITION CONNECTOR

THRU THE BEZEL CAGE ASSEMBLY WITH HEAT SINK

1x3 BEHIND THE BEZEL CAGE

ASSEMBLY WITH HEAT SINK AND LIGHT PIPES

СХР



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About Amphenol Commercial Products

Amphenol's commercial connector products are used in a variety of end user applications including networking, telecom, server & computer, storage & HDD, consumer electronics and entertainment, professional audio & Industrial & Military/Aerospace.

Related Products



38 POSITION CONNECTOR



THRU THE BEZEL CAGE ASSEMBLY WITH HEAT SINK



1x3 BEHIND THE BEZEL CAGE ASSEMBLY WITH HEAT SINK AND LIGHT PIPES

СХР



CAGE AND CONNECTOR ASSEMBLY WITH ROUND PIN HEAT SINK AND ELASTOMER GASKET

Connector Electrical Characteristics

Operating Voltage: 3.3V Operating Current: 1.875A

Connector Mechanical Characteristics

Insertion Force: 80 N Withdrawal Force: 50 N Durability: 200 mating cycles

Material Requirements

Unless otherwise specified, the materials for each component shall be:

Contacts

- o Base material Phosphor Bronze
- Contact Normal Force 40g nominal
- Formed edge
- o Plating
 - Mating area 30 microinches (0.76 μm) μin min Gold over 50 μin (1.27 μm) min Nickel
 - Solder tails 100 microinches (2.54 μm) μin min Tin, over 50 μin (1.27 μm) min Nickel
- Housings: Black color, glass-reinforced, lead-free solder reflow process compatible thermoplastic, UL94V-0 rated
- Resonance dampening feature: Conductive polymer.

Temperature rise: Meets the requirement of $30^{\circ} \text{ C} \Delta \text{T}$ Operating and storage temperature: -40° to $+85^{\circ} \text{ C}$

Process Characteristics

Connectors are tape and reel packaged Cages offered in various options (refer to S6066C) Maximum process temperature during soldering is 260°C for 10 seconds Belly-to-belly placement possible, allowing for two cages to mount on opposite sides of PCB

Resonance Dampening Features

This connector incorporates a ground commoning device to provide better common mode performance and reduced crosstalk at resonance frequencies.

Available Documents

Drawing Numbers: P-U99-B104-XXXX CFP2 Series Connector Contact factory or Authorized Amphenol representative for alternate configurations

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